

**UNCOOLED INFRARED IMAGING
FOR VOLUME APPLICATIONS**Alongside China International
Optoelectronic Expo
SHENZHEN, CHINA

Time	Topics	Speakers	Job Title	Companies
September 7, 2017, SZCEC				
09:00-09:20	Registration / Badge Collection			
09:20-09:30	Welcome and Introduction			Yole Développement and CIOE
Session 1 : Applications Session				
09:30-09:45	Uncooled IR Imaging Market Perspectives	Dr. Eric Mounier	Senior Analyst	Yole Développement
09:45-10:10	State of the art of High End Thermal Image Sensors performances in mass production	Sebastien Tinnes	Marketing Manager	ULIS
10:10-10:35	The Status and Challenges of Thermal Imaging in Security Applications	Dr. Guo Haixun	Product Director of Thermal Imaging	HIK Vision
10:35-11:00	Progress on low cost Thermopile Arrays for high volume applications – eg. office automation, person detection and thermal imaging	Joerg Schieferdecker	CEO and Co-Founder	Heimann Sensors
11:00-11:30	Tea break and networking			
11:30-11:55	New ultra-compact infrared cameras with 500 nm spectral response for metal industry	Torsten Czech	Head of Product Management,	Optris
11:55-12:20	Uncooled Infrared Imaging System for Forest Fire Detection and Monitoring	Wang You	Uncooled Infrared Imaging Senior Expert	JIR Infrared
12:20-12:30	Sponsor presentation			Sunny Infrared Optics
12:30-13:30	Lunch and Networking			
Session 2: New Advances in Infrared Technologies				
13:30-13:55	Ion Beam Deposition of VOx films for uncooled bolometer and thermal sensor applications	Dr David I C Pearson	Ion Beam Senior Technologist,	Oxford Instruments Plasma Technology
13:55-14:20	Modern Assembly Technology for Packaging of IR Microbolometers	Alex Voronel	Director of Global Sales	SST Vacuum Reflow Systems

**UNCOOLED INFRARED IMAGING
FOR VOLUME APPLICATIONS**Alongside China International
Optoelectronic Expo
SHENZHEN, CHINA

14:20-14:45	Prospect of commercial chalcogenide glasses used for uncooled infrared imaging system	Rongping Wang	Senior Fellow	The Australian National University
14:45-15:10	MOEMS components with subwavelength structures for hyperspectral imaging	Steffen Kurth	Department Manager	Fraunhofer Institute for Electronic Nano Systems (ENAS)
15:10-15:15	Sponsor time			
15:15-16:00	Tea break and networking			
16:00-16:25	Atomic Layer Deposition of Thin Films for Infrared Applications	Kari Koski	Technical Sales Manager	Beneq
16:25-16:50	Technologies for Thermal Imaging Packages	Ignace Dupon	Europe/Asia Sales Director	EGIDE
16:50-17:15	High-Performance Readout Circuits for Gryogenic & Uncooled IRFPA	Wengao LU	Associate Professor, Deputy Director	Pekin University
17:15-18:15	Cocktail and networking			

1) Early bird Rate (before August 10): EUR 215(1600 RMB).

2) Standard Rate (after August 10): EUR 265(2000 RMB).

Note: The ticket will include participation, forum documents, translation, speakers' PPT file, lunch, and tea break, cocktail, etc.

Sponsorship and registration:

Please refer to the [sponsorship opportunities](#) and register [here](#).

More Information please contact:

	Shirly Yi (Ms.)	Derek Deng (Mr.)
Email:	Shirly.Yi@cioe.cn	Derek.Deng@cioe.cn
Tel:	86-755-88242569	86-755-88242571